Encapsulation Options

**Advantages:**
- Choose the encapsulation style that meets your prototyping needs
- Mix and match multiple encapsulation options on the same assembly order
- Assembly turn times from 8 hours to 3 days available

**Flattened/Remolded** (fully encapsulated with filled epoxy using QP Technologies' proprietary molding process)
- Test socket compatible/meets JEDEC mechanical standards
- Suitable for customer samples, preproduction runs, etc.
- Auto-handling compliant
- Electrical performance equivalent to production package
- Optional marking/branding service available

**Glob Top** (fully encapsulated with filled epoxy – domed-top surface)
- Electrical performance equivalent to production package
- Optional marking/branding service available
- Suitable for chip-on-board applications

**Partial Open Cavity** (encapsulated with filled epoxy in selected areas)
- FIB ready, UV erasable
- Ideal for circuit repair, visual inspection, emission studies, etc.
- Wires partially protected from mechanical damage

**Open Cavity with Frame or Lid** (no encapsulant, custom frame and/or lid)
- Die and wires protected, yet accessible
- Ease of probing die and chip
- Test socket compatible
- FIB ready, UV erasable
- Ideal for circuit repair, visual inspection, emission studies, etc.
- Suitable for MEMS applications

**Open Cavity** (wire-bonded chip with no encapsulant, die is exposed)
- Ease of probing die and chip
- FIB ready, UV erasable
- Ideal for circuit repair, visual inspection, emission studies, etc.

**Clear Encapsulant** (encapsulated with nonfilled epoxy)
- Easy wire-bonding verification
- Visual sample of assembled product
- Eliminates need for X-ray wire-length measurements
- Lower dielectric constant
- Suitable for IR or visual light transmission applications